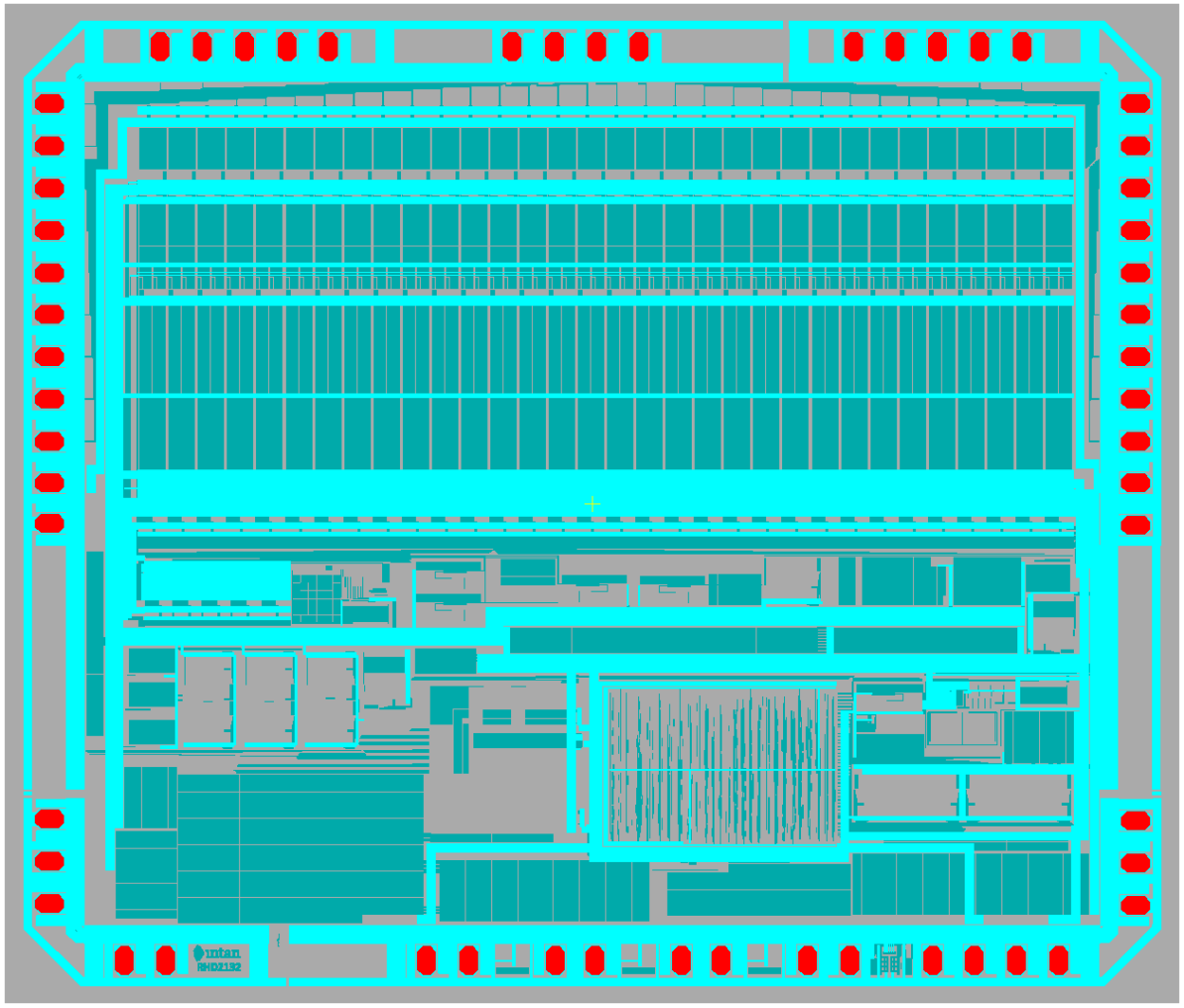
Intan Technologies RHD2132 Bare Die

Approximately 4.8 mm



Approximately 4.1 mm

Gray = approximate outline of die (may vary from die to die due to variations in sawing)

Yellow Cross = center of design (may not coincide precisely with center of die due to variations in sawing)

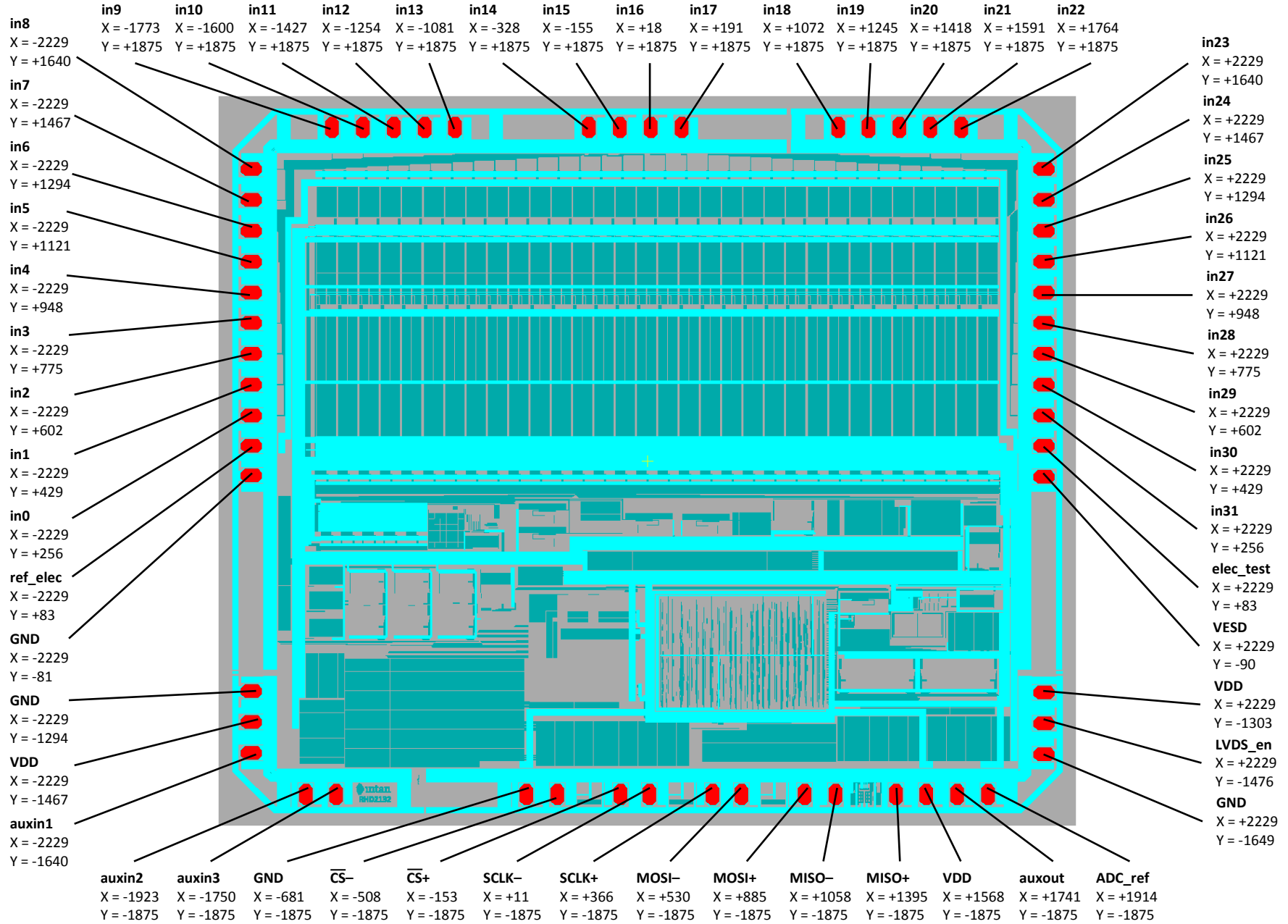
Blue, Green = top metal layers (highly visible)

Red = glass openings for bond pads

Each die is 0.20 mm (8 mils) thick

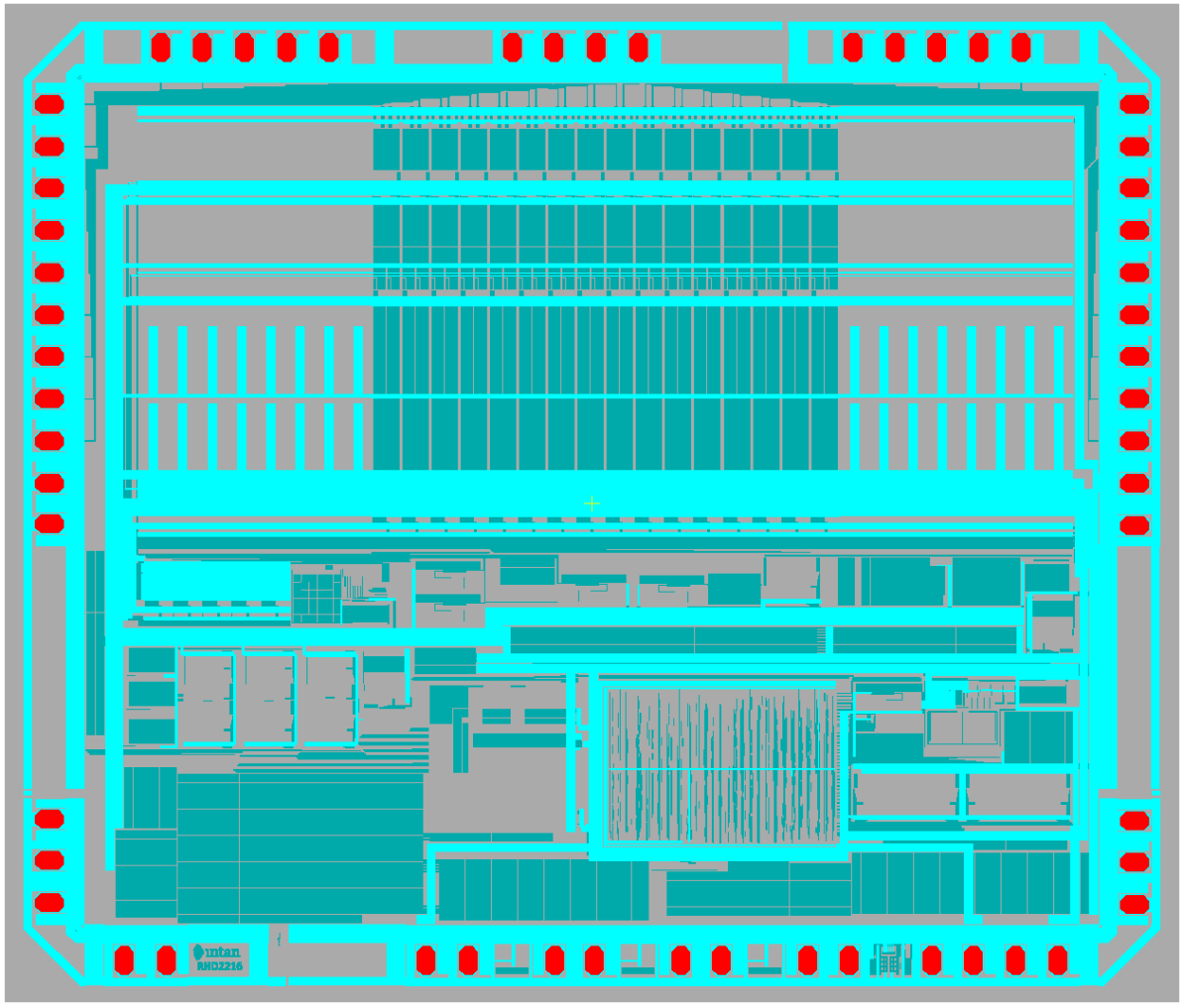
RHD2132 Coordinates of Bond Pad Centers, Relative to Center of Design

dimensions in microns



Intan Technologies RHD2216 Bare Die

Approximately 4.8 mm



Approximately 4.1 mm

Gray = approximate outline of die (may vary from die to die due to variations in sawing)

Yellow Cross = center of design (may not coincide precisely with center of die due to variations in sawing)

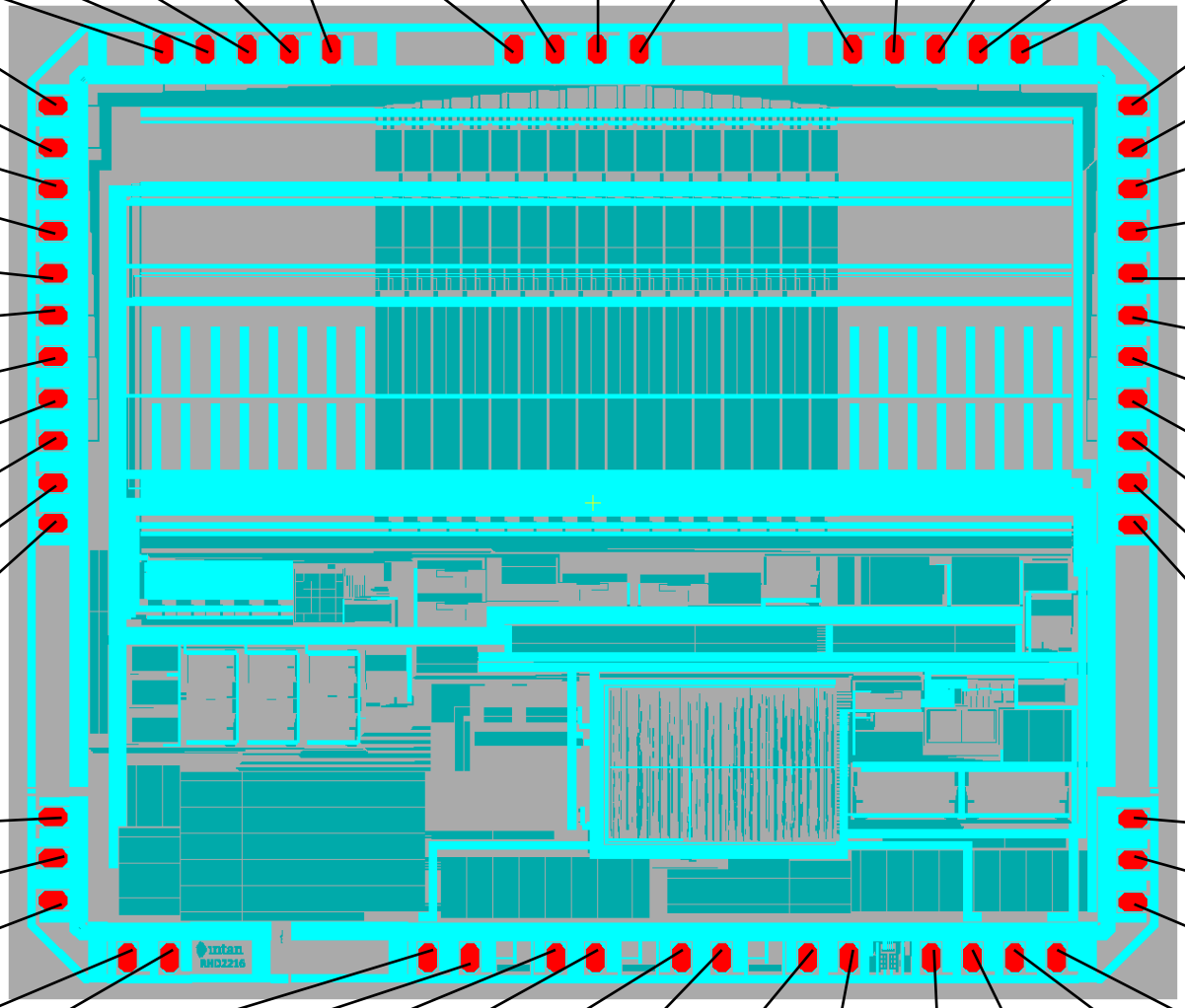
Blue, Green = top metal layers (highly visible)

Red = glass openings for bond pads

Each die is 0.20 mm (8 mils) thick

RHD2216 Coordinates of Bond Pad Centers, Relative to Center of Design

dimensions in microns

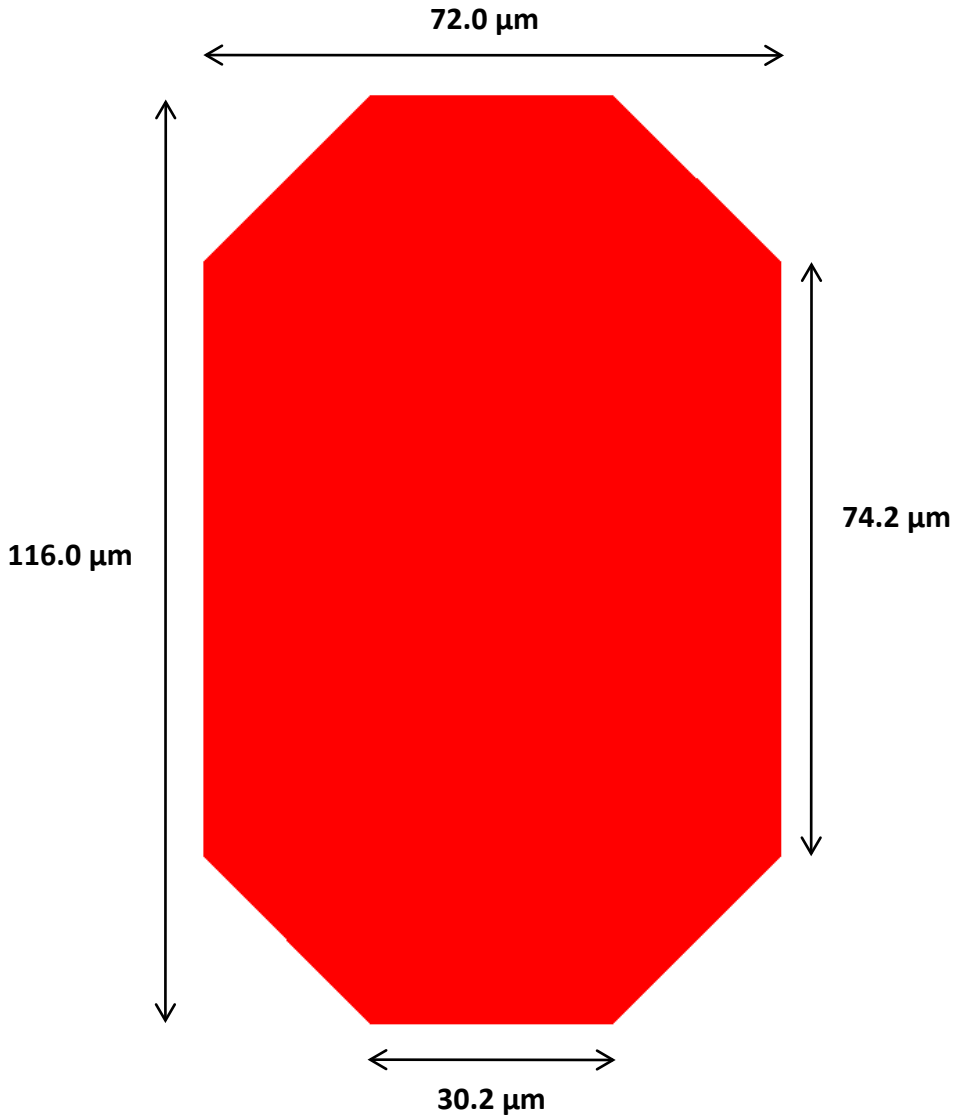


in4+ X = -2229 Y = +1640	**in4–** X = -1773 Y = +1875	**in5+** X = -1600 Y = +1875	**in5–** X = -1427 Y = +1875	**in6+** X = -1254 Y = +1875	**in6–** X = -1081 Y = +1875	**in7+** X = -328 Y = +1875	**in7–** X = -155 Y = +1875	**in8+** X = +18 Y = +1875	**in8–** X = +191 Y = +1875	**in9+** X = +1072 Y = +1875	**in9–** X = +1245 Y = +1875	**in10+** X = +1418 Y = +1875	**in10–** X = +1591 Y = +1875	**in11+** X = +1764 Y = +1875
in3– X = -2229 Y = +1467														
in3+ X = -2229 Y = +1294														
in2– X = -2229 Y = +1121														
in2+ X = -2229 Y = +948														
in1– X = -2229 Y = +775														
in1+ X = -2229 Y = +602														
in0– X = -2229 Y = +429														
in0+ X = -2229 Y = +256														
ref_elec X = -2229 Y = +83														
GND X = -2229 Y = -81														
GND X = -2229 Y = -1294														
VDD X = -2229 Y = -1467														
auxin1 X = -2229 Y = -1640														
	auxin2 X = -1923 Y = -1875	**auxin3** X = -1750 Y = -1875	**GND** X = -681 Y = -1875	**$\overline{CS}$–** X = -508 Y = -1875	**$\overline{CS}$+** X = -153 Y = -1875	**SCLK–** X = +11 Y = -1875	**SCLK+** X = +366 Y = -1875	**MOSI–** X = +530 Y = -1875	**MOSI+** X = +885 Y = -1875	**MISO–** X = +1058 Y = -1875	**MISO+** X = +1395 Y = -1875	**VDD** X = +1568 Y = -1875	**auxout** X = +1741 Y = -1875	**ADC_ref** X = +1914 Y = -1875

in11– X = +2229 Y = +1640														
in12+ X = +2229 Y = +1467														
in12 – X = +2229 Y = +1294														
in13+ X = +2229 Y = +1121														
in13– X = +2229 Y = +948														
in14+ X = +2229 Y = +775														
in14– X = +2229 Y = +602														
in15+ X = +2229 Y = +429														
in15– X = +2229 Y = +256														
elec_test X = +2229 Y = +83														
VESD X = +2229 Y = -90														
VDD X = +2229 Y = -1303														
LVDS_en X = +2229 Y = -1476														
GND X = +2229 Y = -1649														

Bond Pad Dimensions

Bond pad metal: AlCu (99.5% aluminum, 0.5% copper)



Minimum bond pad pitch (center to center) on 16- and 32-channel chips: 173 µm